INTERIM REPORT 2010

1 January – 30 June

KEY FIGURES

in € million	Q2 / 10	Q2 / 09	Change	6M / 10	6M / 09	Change
Continuing operations						
Order entry	50.6	23.9	111.7%	82.9	39.9	107.8%
Order backlog as of 06/30	–	–	–	89.9	57.7	55.8%
Total sales	37.7	24.6	53.3%	59.6	47.1	26.5%
Sales margin	4.8%	2.8%	2.0%-points	1.8%	-0.6%	2.4%-points
Gross profit	13.3	9.7	37.1%	20.1	18.9	6.3%
Gross margin	35.3%	39.4%	-4.1%-points	33.7%	40.1%	-6.5%-points
Costs of sales	24.4	14.9	63.8%	39.5	28.2	40.1%
R&D costs	1.8	1.1	63.6%	3.3	2.3	43.5%
Continuing operations						
EBITDA	5.2	2.1	147.6%	6.8	2.6	161.5%
EBITDA margin	13.8%	8.5%	5.3%-points	11.4%	5.5%	5.9%-points
EBIT	3.5	1.0	250.0%	3.5	0.2	> 250%
EBIT margin	9.3%	4.1%	5.2%-points	5.9%	0.4%	5.5%-points
Earnings after tax	1.8	0.7	157.1%	1.1	-0.3	> 250%
Earnings per share	0.10	0.04	150.0%	0.06	-0.02	> 250%
Continuing and discontinued operations						
Earnings after tax	1.6	-0.1	> 250%	0.5	-1.1	145.5%
Earnings per share	0.09	0.00	–	0.03	-0.07	142.9%
Balance sheet and cash flow						
Equity	–	–	–	96.6	89.9	7.5 %
Equity ratio	–	–	–	59.6 %	62.8 %	-3.2 %-points
Return on equity	1.7 %	-0.1 %	1.8 %-points	0.5 %	-1.2 %	1.7 %-points
Balance sheet total	–	–	–	162.1	143.1	13.3 %
Net cash	–	–	–	25.6	13.8	85.5 %
Free cash flow *	7.3	2.1	247.6 %	6.0	4.0	50.0 %
Further key figures						
Investments**	0.6	0.6	0.0 %	1.2	2.5	-52.0 %
Investment ratio	1.6 %	2.4 %	-0.8 %-points	2.0 %	5.3 %	7.1 %-points
Depreciation	1.6	1.2	33.3 %	3.3	2.5	32.0 %
Employees as of 06/30 ***	–	–	–	581	499	16.4 %
Employees as of 06/30 ****	–	–	–	581	623	-6.7 %

* before consideration of purchase or sale of available-for-sale securities and before consideration of extra-ordinary items for purchase or sale of subsidiaries

** before consideration of the acquisition of HamaTech and purchase of land and facility in Sternenfels

*** continuing operations

**** continuing and discontinued operations

CONTENTS

FOREWORD OF THE MANAGEMENT BOARD

Dear Shareholders, Ladies and Gentlemen,

After the first quarter of the current 2010 fiscal year was dominated by the successful conclusion of two strategic investment and divestment projects, it stood to reason that the second quarter would be shaped by several internal structural changes. And so, as early as mid-May – just three months after the acquisition of HamaTech APE – the production sites at Vaihingen and Sternenfels were amalgamated without complications. In addition, the subsidiary in Taiwan became our first foreign sales company to successfully implement the Group-wide SAP system. Furthermore, the relocation of the Substrate Bonder division from the USA to Germany, which was announced in June, is currently being implemented and will be completed by the end of this fiscal year. At the same time, the North American sales and applications center is being moved from Waterbury, Vermont, to Sunnyvale, California. Both steps will have a major impact on streamlining our corporate structure and represent the final phase of our strategic restructuring.

Along with these measures, in mid-May we successfully placed a total of 1,701,912 common bearer shares – with a calculated par value of €1.00 per share and profit-sharing rights beginning on January 1, 2010 – with German and international investors via an increase in capital stock from approved capital, excluding subscription rights. The gross inflow of funds of €6.8 million is being used in particular to refinance the HamaTech acquisition and fund additional corporate growth. At the end of May, a loan agreement for €4.5 million was concluded with a local bank in order to finance the newly acquired business property in Sternenfels.

The Quarter in Figures

The second quarter of 2010 went well for our Company from a financial point of view as well. The rising demand for SUSS MicroTec equipment, which was already evident in the first quarter of 2010, was even more robust in the second quarter. Order entry increased in the months from April to June 2010 by approximately 112% to €50.6 million after €23.9 million in the same period of the previous year. In particular, the regions of Taiwan, China, and Rest of Asia were drivers of the strong demand. Sales in the second quarter totaled €37.7 million, exceeding the previous year's quarterly figure by approximately 53% (Q2 2009: €24.6 million).

left:
Michael Knopp
CFO

right:
Frank Averdung
CEO

A mid-year review paints an equally positive picture: in the first six months of 2010, order entry of €82.9 million surpassed the €39.9 million total for the same period of the previous year by approximately 108%. Compared with the first half of 2009, sales increased by approximately 27% from €47.1 million to €59.6 million. The order backlog as of June 30, 2010 thus amounted to €89.9 million (June 30, 2009: €57.7 million).

Including extraordinary effects of €1.5 million, earnings before interest and taxes (EBIT) improved to €3.5 million (H1 2009: €0.2 million). Extraordinary effects in the first half of the year primarily consisted of the following:

+ Gain of bargain purchase of €2.7 million resulting from the initial consolidation of HamaTech APE
+ Restructuring expenses of €-0.3 million resulting from the amalgamation of the production sites in Vaihingen and Sternenfels
+ Restructuring expenses of €-0.9 million related to the relocation of the Substrate Bonder division from the USA to Germany

Excluding these extraordinary effects, EBIT came to €2.0 million. Earnings after taxes (EAT) amounted to €1.1 million, compared with €-0.3 million in the corresponding period of the previous year. Basic earnings per share (EPS) therefore totaled €0.06 (H1 2009: €-0.02).

Free cash flow before the inclusion of securities and extraordinary effects from M&A activities came to €6.0 million at the end of the first half-year after €4.0 million in the same period of the previous year. As of June 30, 2010, the SUSS MicroTec Group therefore had cash and interest-bearing securities of €37.1 million (December 31, 2009: €31.1 million). The net cash position grew significantly in comparison to the end of the 2009 fiscal year from €18.4 million to €25.6 million (H1 2009: €13.8 million).

Outlook

In view of the strong order entry in the second quarter of 2010, we have raised our annual forecast for the full year. For the current year we now expect sales of approximately €140 million as well as positive earnings before interest and taxes (EBIT) despite one-off restructuring expenses of approximately €7.5 million. We will also be in a position to generate positive free cash flow in the 2010 fiscal year.

Garching, Germany, August 2010

Frank Averdung
Chief Executive Officer

Michael Knopp
Chief Financial Officer

HIGHLIGHTS

New MA100e Mask Aligner Introduced for the Production of High Brightness LEDs

Based on SUSS MicroTec's proven Mask Aligner technology, the new fully automatic MA100e Gen2 Mask Aligner was introduced at the beginning of June. The next generation of the proven MA100e, which was specially developed for the production of high brightness LEDs, processes wafer sizes up to 4" at an industry-leading throughput of 145 wafers per hour and reduced cycle times. The new MA100e Gen2 saves valuable processing time during production as a result of its very powerful exposure optics, the ability to process wafers extremely rapidly, and very short changeover times between the individual substrate sizes. In addition, special non-contact handling protects the highly sensitive and expensive wafers, which are used for LED production, thus contributing significantly to increased output. As a result, the new system optimally fulfills the requirements of the LED industry for an inexpensive, technically sophisticated, and fully automated processing solution.

Market Launch of the New MaskTrack Pro BD at SEMICON West

During SEMICON West – the world's largest semiconductor trade fair – in San Francisco, HamaTech APE, a wholly owned subsidiary of SUSS MicroTec AG, introduced its latest innovation for mask cleaning and integrity. The new MaskTrack Pro Bake/Develop (BD), which represents a refinement of the extremely successful MaskTrack Pro cleaning platform, was

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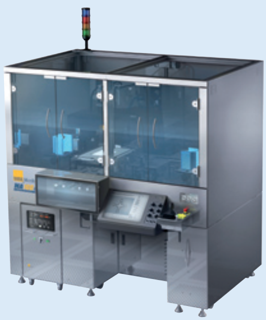


2

1: The new MA100e Gen2 Mask Aligner

2: MaskTrack Pro BD – the state-of-the-art photomask cleaning solution of HamaTech APE specially designed for device nodes < 22nm

3: The new production facility at the Sternenfels site developed especially for the demanding mask cleaning and integrity of 193i immersion technology and extreme ultraviolet (EUV) lithography. The new system thus now covers bake and develop processes, which are critical to success and are necessary for next generation lithography. With MaskTrack Pro BD, a unique compensation process is being introduced that ensures maximum temperature uniformity at the mask level during treatment and therefore enables the precise matching of individual process parameters. As a result of this special approach, MaskTrack Pro BD guarantees above-average precision in transferring patterns from mask to substrate, thus providing significantly higher output for customers. The first MaskTrack Pro BD will be delivered to Asia as early as the end of 2010.

3

Relocation of the Substrate Bonder Division from the USA to Germany

In mid-June, the Company announced its decision to move its Substrate Bonder division, based in Waterbury, Vermont (USA), to Germany. In the course of the planned restructuring, the research and development, production and product management functions of the Bonder product lines will be relocated to Sternenfels (Baden-Württemberg), Germany. At the same time, the North American service and sales activities as well as the applications center are moving from Waterbury to Sunnyvale, California. The decision to combine the Substrate Bonder, Coater/Developer, and Photomask Equipment product lines at the newly acquired Sternenfels site has been made in the interest of optimizing and simplifying the corporate structure and reducing the number of development and manufacturing sites from the existing four in January 2010 to two highly efficient sites in Germany for the future. Furthermore, by bundling the product lines at one site, the Company will be able to achieve technology and production synergies and react faster and more flexibly to market demands. In addition to the cost advantages for R&D, the production site in Sternenfels also provides the physical premises necessary to take advantage of the growth potential available in the area of 3D integration.

INVESTOR RELATIONS

Shareholders' Meeting Approves Changes to the Articles of Incorporation

Approximately 80 shareholders, shareholder representatives, bank representatives, and guests accepted the invitation to this year's ordinary Shareholders' Meeting, which took place on June 23, 2010 in the Haus der Bayerischen Wirtschaft (House of the Bavarian Economy) in Munich. In total, 6.1 million voting shares (approximately 33% of the Company's equity capital) were represented.

In addition to discharging the Management Board and Supervisory Board from liability for the 2009 fiscal year and appointing auditors for the individual and consolidated financial statements, this year the amendment of the articles of incorporation pursuant to the German Act on Implementing the Shareholders' Rights Directive (ARUG) was on the agenda. All resolution proposals were approved by at least 99% of the voting rights represented at the Shareholders' Meeting. The originally scheduled agenda item 6, which dealt with the creation of new conditional capital as well as the authorization to issue convertible and/or optional bonds, had already been removed from the agenda prior to the Shareholders' Meeting and was thus not presented for resolution. In his statement of accounts, Chief Executive Officer Frank Averdung detailed the main developments and results of the past fiscal year and the first quarter of 2010. The report focused in particular on the investment and divestment projects started in fiscal year 2009 and completed in the current 2010 fiscal year, as well as on the relocation of the Substrate Bonder division from the USA to the Sternenfels site in Germany, which was announced in mid-June.

Successful Increase in Capital Stock from Approved Capital

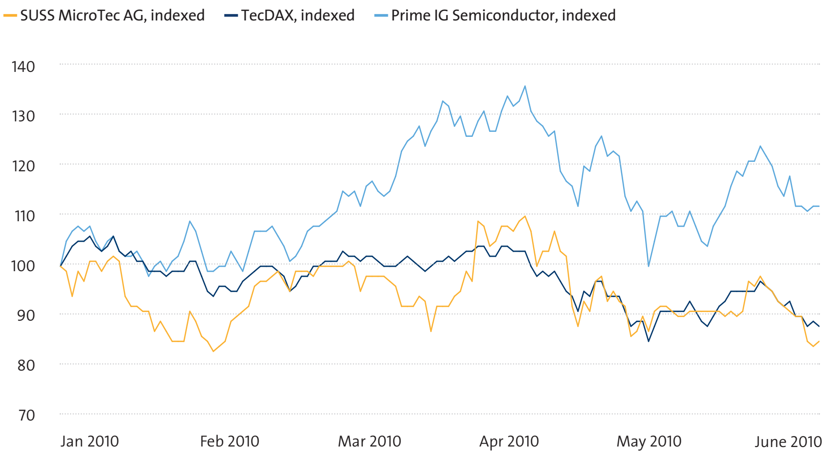
On May 11, 2010, SUSS MicroTec AG carried out an increase in capital stock without subscription rights from approved capital as part of an accelerated book-building procedure. As a result, a total of 1,701,912 common bearer shares were issued with a calculated par value of €1.00 per share and profit-sharing rights beginning on January 1, 2010. The increase in capital stock, which was carried out at short notice, was needed to refinance the HamaTech acquisition and provide further financing for corporate growth. The new shares were successfully placed with German and international investors at a price of €4.00 per share. The gross inflow of funds for the Company amounted to a total of approximately €6.8 million. The new shares were listed on May 25, 2010. They were made equivalent with the old shares on June 24, 2010 following the ordinary Shareholders' Meeting. As a result, the Company's subscribed capital increased from €17,019,126.00 to the new amount of €18,721,038.00.

The SUSS MicroTec Share

The SUSS MicroTec share began the 2010 fiscal year at a price of €4.45. Despite positive corporate news (the sale of the loss-making Test Systems division), the share lost ground slightly in the first three months of the year and closed approximately 6% lower at €3.88 on March 31, 2010. At the beginning of the second quarter there was a temporary change in direction for the share performance. On April 14, the investor magazine "Der Aktionär" (The Shareholder) set off some real fireworks with the share price. After the magazine added the SUSS MicroTec share to its model portfolio, the share surged by 12% to €4.84 with extraordinarily high daily trading volumes. Finally, on April 26, the share reached its high for the year so far of €4.95. In the subsequent months, concerns about the creditworthiness of the PIIGS countries (Portugal, Italy, Ireland, Greece, and Spain) depressed the overall stock market mood. Against this backdrop, the SUSS MicroTec share lost ground again and closed the quarter on June 30, 2010 at €4.00, representing a drop of approximately 10% from the closing price at the end of 2009.

SUSS MicroTec Share Performance in 2010

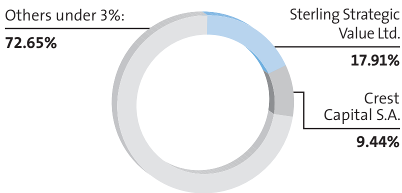
SUSS MicroTec share price on January 1, 2010: €4.45)



The TecDAX German stock market index similarly ended the first half of 2010 with a drop of approximately 11%, while the Prime IG Semiconductor sector index managed to record an increase of approximately 12% in the first six months of the year compared with the closing price for 2009.

The average daily trading volume of SUSS MicroTec shares on all German stock exchanges increased in the second quarter of 2010 to 125,583 shares (Q2 2009: average daily trading volume of 46,972 shares). In the first half of 2010, the average daily trading volume for the share was 105,375 shares.

Ownership Information as of June 30, 2010 in %



Share Ownership by Officers and Related Parties as of June 30, 2010

	Shares	Options
Management Board		
Frank Averdung	27,500	67,500
Michael Knopp	22,500	97,500
Supervisory Board		
Dr. Stefan Reineck	9,600	40,000
Jan Teichert	0	0
Sebastian Reppegather	0	0

CONSOLIDATED INTERIM MANAGEMENT REPORT of SUSS MicroTec AG

Overview of Business Development

The rising demand for SUSS MicroTec equipment, which was already evident in the first quarter of 2010, has remained encouragingly strong in this year's second quarter. Order entry increased in the months from April to June 2010 by approximately 112% to €50.6 million after €23.9 million in the same period of the previous year. Sales in the second quarter totaled €37.7 million, exceeding the previous year's quarterly figure by approximately 53% (Q2 2009: €24.6 million).

A mid-year review paints just as encouraging a picture: in the first six months of 2010, order entry of €82.9 million surpassed the €39.9 million total for the same period of the previous year by approximately 108%. Compared with the first half of 2009, sales increased by approximately 27% from €47.1 million to €59.6 million. The order backlog as of June 30, 2010 amounted to €89.9 million (June 30, 2009: €57.7 million).

Gross profit in the first half of 2010 improved by approximately 6% to €20.1 million compared with the previous year's period (H1 2009: €18.9 million). However, the gross profit margin fell from 40.1% to its current figure of 33.7%, reflecting relatively low-margin individual Bonder systems, which were delivered in the second quarter of 2010 as part of strategic R&D cooperative agreements. Including extraordinary effects of € 1.5 million, earnings before interest and taxes (EBIT) improved significantly to €3.5 million (H1 2009: €0.2 million). Extraordinary effects in the first half of the year primarily consisted of the following:

+ Gain of bargain purchase of €2.7 million resulting from the initial consolidation of HamaTech APE
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Excluding these extraordinary effects, EBIT came to €2.0 million. Earnings after taxes (EAT) amounted to €1.1 million, compared with €-0.3 million in the corresponding period of the previous year. Basic earnings per share (EPS) therefore totaled €0.06 (H1 2009: €-0.02).

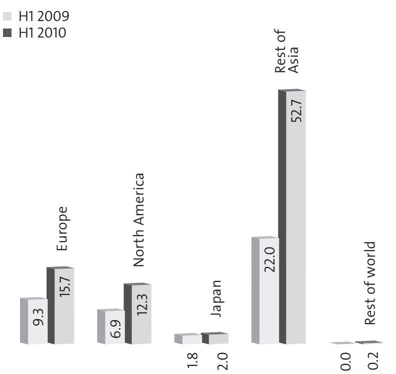
Free cash flow before inclusion of securities and extraordinary effects from M&A activities came to €6.0 million at the end of the first half-year after €4.0 million in the same period of the previous year. As of June 30, 2010, the SUSS MicroTec Group therefore had cash and interest-bearing securities of €37.1 million (December 31, 2009: €31.1 million). The net cash position grew significantly in comparison to the end of the 2009 fiscal year from €18.4 million to €25.6 million (H1 2009: €13.8 million).

Orders Position and Sales by Region

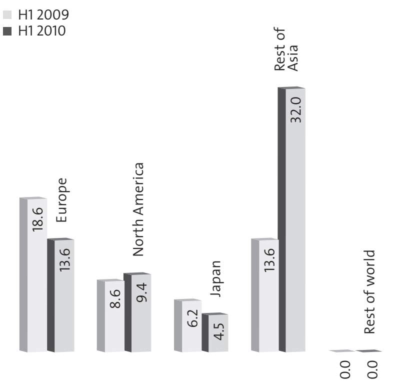
The strong orders position in the first half of 2010 was primarily driven by the Rest of Asia region, which essentially encompasses Taiwan, China, and Malaysia and which recorded an overall increase in orders of 139.5% compared to the corresponding period of the previous year. Although the regions of North America (+78.3%) and Europe (+68.8%) each recorded high double-digit growth rates in order entry, growth in the Japan region of +11.1% compared to the previous year's period was relatively modest.

The regional distribution of sales in the first six months offers a mixed picture. While the regions of Europe (-26.9%) and Japan (-27.4%) still recorded significant declines compared to the first half of 2009, the regions of North America and Rest of Asia reported sales increases of 9.3% and 135.3%, respectively.

Order Entry by Region (Continuing operations) in € million



Sales by Region (Continuing operations) in € million



Business Development in the Individual Divisions

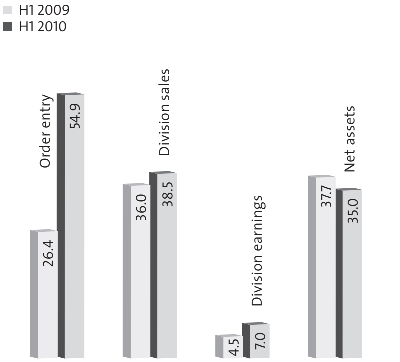
Lithography

The Lithography division includes the development, manufacture, and sale of the Mask Aligner, Developer, and Coater product lines. These product lines are developed and produced in Germany at the locations in Garching near Munich and more recently in Sternenfels. The relocation of Coater and Developer production from Vaihingen an der Enz to the newly acquired production building in neighboring Sternenfels was completed in mid-May 2010 without complications.

The Lithography division recorded encouraging growth rates both in order entry and sales in the first half of 2010. Order entry of €54.9 million was up 106.8% compared with the figure for H1 2009 of €26.4 million. Asian production customers in particular were drivers of the strong demand. Division sales in the first half of the year amounted to €38.5 million after

€36.0 million in the corresponding quarter of the previous year. Division earnings improved from €4.5 million in the first six months of the previous year to €7.0 million.

Lithography Division Overview in € million

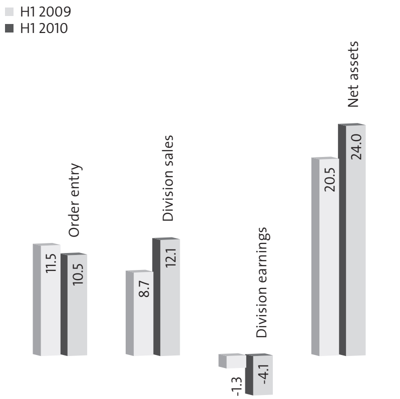


Substrate Bonder

The Substrate Bonder division comprises the development, production, and sale of the Substrate (Wafer) Bonder product line and is currently still located in Waterbury, Vermont (USA). The relocation of Bonder development and production to Sternenfels, which was announced in mid-June, is being implemented at present and should be completed by the end of this fiscal year. Both Bonder sales and the North American service and applications center will be relocated to California as part of this move.

Although order entry of €10.5 million in the Substrate Bonder division declined slightly compared to the first half of the previous year (H1 2009: €11.5 million), sales improved in the same period by approximately 39% to €12.1 million (H1 2009: €8.7 million). Despite this good sales performance, division earnings fell from €-1.3 million to €-4.1 million. The weaker earnings development was due in particular to the very low margins for several large production systems, which were delivered to strategic R&D partners in the second quarter of 2010, as well as extraordinary expenses of €0.9 million in connection with the relocation of the division to Germany.

Substrate Bonder Division Overview in € million

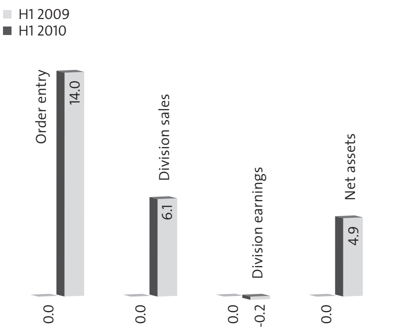


Photomask Equipment

The Photomask Equipment division includes the development, manufacture, and sale of the HMx, ASx, MaskTrack, and MaskTrack Pro product lines of HamaTech APE GmbH & Co. KG, which was acquired on February 15, 2010. The development and production of specialized systems for the cleaning and processing of photomasks for the semiconductor industry is conducted at the Sternenfels site near Stuttgart.

The Photomask Equipment division developed very favorably in the four-month period since initial consolidation. At the end of June 2010, order entry totaled €14.0 million. Division sales amounted to €6.1 million. For purposes of comparison: in the previous 2009 fiscal year, HamaTech APE generated annual sales of €11.0 million. In terms of earnings, the division made a small loss of €0.2 million in the period under review.

Photomask Equipment Division Overview in € million

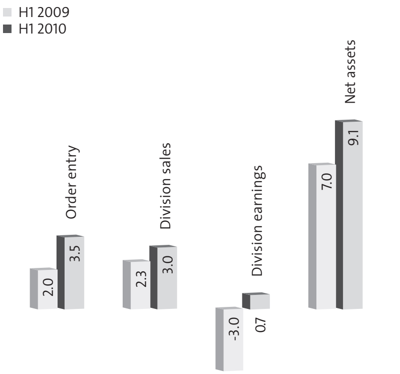


Others

The Others division comprises the Mask business in Palo Alto, California (USA), which caters to the semiconductor industry, and the Micro-optics activities at the Neuchâtel, Switzerland location as well as the C4NP business and the costs for central Group functions that generally cannot be attributed to the main divisions.

The Others division performed positively compared to the first half of 2009 in terms of both order entry and sales. Order entry improved from €2.0 million to €3.5 million. Division sales after the first six months of 2010 amounted to €3.0 million after €2.3 million in the corresponding period of the previous year. Compared to H1 2009, the Photomask business experienced a slight decline of €0.2 million in both order entry and sales to €1.2 million (H1 2009: €1.4 million). By contrast, order entry in the Micro-optics business grew by €1.4 million to €2.1 million (H1 2009: €0.7 million), while sales increased by €0.9 million to €1.6 million (H1 2009: €0.7 million). Badwill totaling €2.7 million related to the initial consolidation of HamaTech APE had a positive impact on division earnings, which amounted to €0.7 million in the first half of 2010 after €-3.0 million in the corresponding period of 2009.

Others Division Overview in € million



Report on the Earnings, Assets, and Financial Position of the Group

Earnings Position

Sales generated by the SUSS MicroTec Group in the first half of 2010 demonstrated a significant upward trend. In the first six months of the current fiscal year, the SUSS MicroTec Group achieved sales of €59.6 million. This included sales of €6.1 million in the Photomask Equipment division, which has been part of the SUSS MicroTec Group since the acquisition of HamaTech APE GmbH & Co. KG on February 15, 2010. Excluding the Photomask sales, sales in the first half of 2010 totaled €53.5 million after approximately €47.1 million in the previous year's period, representing a rise of approximately 13.6%.

EBIT in the first half of 2010 amounted to €3.5 million (continuing activities). The initial consolidation of HamaTech APE GmbH & Co. KG on March 1, 2010, which led to gain of bargain purchase of €2.7 million, had a positive impact. However, restructuring expenses of €0.9 million, which were incurred in connection with the relocation of the Substrate Bonder division and the North American sales and service organization from Waterbury, Vermont (USA) to Sternenfels and California, respectively, had a negative effect on earnings. Furthermore, the amalgamation of the Vaihingen and Sternenfels sites resulted in additional expenses of €0.3 million.

Adjusted for these extraordinary effects, the EBIT in the first six months of the current fiscal year came to approximately €2.0 million (after €0.2 million in the same period of the previous year).

As in previous quarters, the largest sales driver was the Lithography division, which produced sales of €38.5 million and an EBIT of €7.0 million. In the first half of the previous fiscal year, the SUSS MicroTec Group's Lithography division generated sales of €36.0 million and an EBIT of €4.5 million.

Sales increases were also recorded in the Substrate Bonder division: in the first six months of the current fiscal year, sales totaled €12.1 million (after €8.7 million in the first half of 2009). Earnings in the Substrate Bonder division were reduced by high expenses for cooperative agreements with IMEC and ITRI and high development costs related to thin wafer handling. In addition, earnings reflected restructuring expenses of €0.9 million related to the relocation of the Substrate Bonder division. As a result of these high expenses, the EBIT deteriorated further and amounted to -€4.1 million (after -€1.3 million in the corresponding period of the previous year).

Sales developments in the new Photomask Equipment division were very encouraging. In the four months since the initial consolidation, the Photomask Equipment division contributed €6.1 million to consolidated sales. The Photomask Equipment division's EBIT amounted to -€0.2 million in the first half of 2010.

Cost of sales included write-downs on capitalized development costs of EUR 1.4 million. As such, write-downs on capitalized development costs were approximately €1.3 million higher than new capitalizations, which totaled only €0.1 million in the first six months of the current fiscal year. In the first half of 2009, capitalized development costs came to €1.0 million and were thus approximately as high as the write-downs, which also amounted to €1.0 million.

The gross profit increased compared with the previous year's period by €1.2 million, amounting to €20.1 million in the first half of 2010. However, the gross profit margin shrank from 40.1% in the same period of the previous year to 33.7%. The main reason for the decline in the gross profit margin was the Substrate Bonder division, which processed strategically important orders with IMEC and ITRI involving high cost of sales.

It was possible to keep administrative and selling costs at a low level due to the systematic ongoing implementation of the cost-saving program. Overall, administrative and selling costs of €16.4 million were incurred, representing an expense ratio of 28% relative to sales generated. In the same period of the previous year, corresponding costs of €16.0 million were recorded, representing approximately 34% of sales generated.

Research and development costs totaled €3.3 million in the first half of 2010. As a result, they were approximately €1.0 million higher than in the same period of 2009.

Other operating income of €5.5 million included the recognition in profit or loss of gain of bargain purchase of €2.7 million, which resulted from the initial consolidation of HamaTech APE GmbH & Co. KG and the retroactive purchase price adjustment.

The financial result for the first half of 2010 came to -€0.5 million (after €0.0 million in the previous year's period), primarily reflecting higher interest expenses, while interest income was lower than in the previous year.

In the first half of 2010, a tax expense of €1.9 million was recognized. This resulted in a consolidated tax rate that significantly exceeded the average consolidated tax rate of approximately 28%. This development is essentially due to the fact that it was not possible to recognize deferred tax assets for the losses incurred by foreign subsidiaries.

Financial Position

In the first half of the year, the SUSS MicroTec Group succeeded in significantly expanding its net cash position – the balance from cash and cash equivalents, interest-bearing securities, and financial liabilities – to €25.6 million. Compared with December 31, 2009, this meant an increase of €7.2 million.

These developments made it possible to achieve the goal of generating positive free cash flow once again in the first half of the year: Adjusted for extraordinary effects (acquisition of HamaTech, including the land and buildings at Sternenfels and the sale of the Test Systems business) and before inclusion of available-for-sale securities, free cash flow totaled €6.0 million, compared with €4.0 million in the same period of the previous year.

The high level of free cash flow was again essentially due to a high cash inflow from operating activities of €6.5 million (previous year: €6.4 million). In particular the build-up of accounts payable (reduced cash outflow of €4.4 million) and the significant increase in customer down payments (from €12.6 million at the end of 2009 to €17.3 million) had a noticeable impact here. It was also possible to reduce accounts receivable further (adjusted for exchange rate effects) and generate a cash inflow of €1.8 million. A countervailing factor was the build-up of consolidated inventories, which resulted in a cash outflow of €7.6 million. Tools that had already been delivered to customers but for which final acceptance was still outstanding, accounted for the largest share of the increase in inventories. The inventory of these tools rose from €9.8 million at the end of 2009 to the current figure of €12.9 million.

Cash flow from investing activities amounted to -€1.3 million (after -€2.5 million in the first half of 2009), excluding the acquisition of HamaTech APE GmbH & Co. KG as well as the land and buildings in Sternenfels, the sale of the Test Systems business, and investments in securities. Investments were primarily made in tangible assets.

Cash flow from financing activities reflected a cash inflow from the increase in capital stock carried out in May 2010, which resulted in a net inflow of €6.6 million.

Besides cash and cash equivalents of €19.5 million (December 31, 2009: €20.6 million), the Group had credit and guarantee lines of approximately €9.7 million as of the half-year reporting date, which were predominantly secured in line with banking practice and were not bound to financial covenants. The utilization of these credit lines amounted to €2.7 million as of the half-year reporting date and primarily related to down payment guarantees for customer down payments. Thus, the Group has sufficient funds at its disposal to finance the operational business.

Assets Position

Noncurrent assets totaled €45.3 million as of the half-year reporting date and were thus €5.3 million higher than on December 31, 2009. The increase resulted primarily from the purchase of the land and buildings in Sternenfels, which were obtained as part of the acquisition of HamaTech APE and recognized at a cost of €4.5 million. An additional €0.3 million was invested in the newly acquired buildings as part of the relocation of the Vaihingen production site to Sternenfels.

Intangible assets showed an increase of €0.5 million to €14.3 million. The main reasons for this were the technology obtained as part of the HamaTech purchase and the acquisition of an order backlog, which together with acquisition costs were valued at €1.0 million and will be written down on a pro rata basis until the end of their useful life. In addition, capitalized development costs denominated in US dollars rose by approximately €1.0 million as a result of exchange rate effects. Write-downs on capitalized development costs, which totaled €1.4 million in the first six months of the current fiscal year, were a countervailing factor.

Current assets rose by €20.3 million from €96.5 million (December 31, 2009) to €116.8 million as of the half-year reporting date. This was largely due to an inventory increase of €15.9 million to €56.7 million. €5.6 million of this increase related to the inventories of HamaTech APE GmbH & Co. KG, which were added to consolidated assets as a result of the acquisition. An additional increase of €3.0 million resulted from the revaluation of inventories reported in foreign currencies due to changes in exchange rates. Furthermore, inventories of tools that had already been delivered to customers but for which final acceptance was still outstanding rose by approximately €3.1 million to €12.9 million.

Accounts receivable also showed an increase of €14.8 million (December 31, 2009) to €16.6 million. The increase resulted in part from receivables of €1.6 million, which were acquired as part of the HamaTech APE purchase. In addition, changes in exchange rates boosted foreign currency receivables by €1.6 million. However, adjusted for exchange rate and extraordinary effects, the level of receivables declined by €1.4 million.

The SUSS MicroTec Group's portfolio of securities increased in the first six months of the current fiscal year from €10.5 million to €20.3 million. First, SUSS MicroTec AG obtained 747,530 shares in Cascade Microtech Inc., Beaverton, Oregon (USA), which were valued at €2.7 million as of the half-year reporting date, following the sale of shares in SUSS MicroTec Test Systems GmbH. And second, securities amounting to approximately €8.0 million were acquired in the second quarter of 2010 using the free cash flow generated. The securities recognized consist of corporate and government bonds as well as commercial paper.

The shareholders' equity of the SUSS MicroTec Group has grown since December 31, 2009 by €10.6 million to €96.6 million. However, the equity ratio has fallen from 63.1% to 59.6% as a result of the increase in total assets.

The increase in capital stock carried out on May 10/11, 2010 resulted in 1,701,912 shares being issued at a price of €4.00 per share. The gross inflow of funds amounted to €6.8 million. As a result, common stock increased by €1.7 million to €18.7 million. €5.1 million was added to additional paid-in capital. The transaction costs for carrying out the increase in capital stock totaled approximately €0.2 million. They were deducted from additional paid-in capital.

Noncurrent liabilities rose by €1.0 million from €20.0 million to €21.0 million. The increase was primarily due to higher deferred tax liabilities of €0.7 million from the acquisition of HamaTech.

In the first half of 2010, current liabilities grew by €14.0 million to €44.4 million. The high level of accounts payable, which amounted to €11.1 million as of June 30, 2010 (after €4.5 million at the end of 2009), accounted for most of this growth. The revaluation due to exchange rate changes caused these liabilities to increase by €1.1 million.

Other liabilities went up by €6.4 million to €21.3 million in comparison to December 31, 2009. The primary reason for this was the high level of customer down payments, which amounted to approximately €17.6 million as of the half-year reporting date (after €12.6 million at the end of 2009). Furthermore, provisions for personnel expenses rose (due to the reporting date) by €0.9 million to €2.8 million.

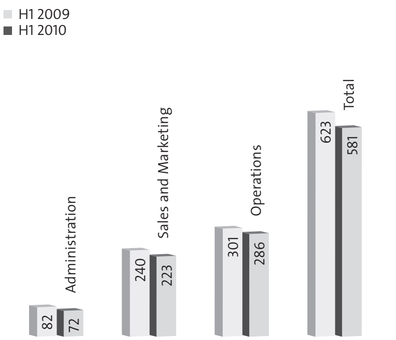
Provisions have shown an increase of €2.8 million to €4.6 million since the beginning of the year. This amount includes the earn-out provision of €0.3 million recognized in connection with the HamaTech acquisition and the restructuring provision of €0.7 million for the relocation of the Substrate Bonder division. Provisions of €0.4 million were recognized for severance payments and other liabilities in connection with the sale of the Test Systems business. In addition, the warranty provision was increased by €0.3 million in response to the rise in sales.

The tax liabilities include tax provisions set up for individual Group companies on the basis of the positive half-year result in 2010.

Group Employees

As of June 30, 2010, the Group had 581 employees (June 30, 2009: 623 employees overall, 499 employees in continuing activities) within the individual Group companies. The increase is almost exclusively attributable to the acquisition of HamaTech APE GmbH & Co. KG.

Group Employees (reporting date 06/30)



Subsequent Events

On May 25/28, 2010, SUSS MicroTec AG concluded a loan agreement with a local bank in order to finance the newly acquired business property in Sternenfels. The loan, which totals €4.5 million, runs until June 30, 2020. It was made available and drawn down on July 6, 2010.

No additional material events requiring disclosure occurred after the end of the interim reporting period.

Risk Report

Global activities in the field of high technology lead to general and current risks for the Company. The Management Board has taken appropriate measures for the purpose of monitoring risks in order to identify developments that may threaten the continued existence of the SUSS MicroTec Group early on.

In risk monitoring, a fundamental distinction is made between general business and industry risks, operating risks, and financial market risks.

General Business and Industry Risks

The Company identifies general business risks as underlying political and economic conditions, cyclical market fluctuations and developments, market positioning, and dependence on the expertise of individuals. These risks are described in the Company's most recent Annual Report in the corresponding Risk Report section.

There were no substantial changes to the risks and opportunities outlined in the most recent Annual Report during the first half of the current fiscal year.

Operating Risks

SUSS MicroTec regards operating risks as those which have an impact on the Group's assets and earnings position as a result of potentially necessary write-downs in the consolidated statement of financial position due to the difficult economic environment. Pricing pressure and legal risks, in particular liability risks, represent additional operating risks. Each of these risk types was outlined in detail in the most recent Annual Report.

The following possible risks were identified in connection with the relocation of the Substrate Bonder division and the North American sales and service organization from Waterbury, Vermont (USA) to Sternenfels and California, respectively.

In order to successfully relocate and continue the Substrate Bonder division, SUSS MicroTec needs to preserve the expertise of its North American employees and transfer it to the employees who will in future be working in Sternenfels and California. To ensure that knowledge is transferred adequately, it is necessary that a large number of the employees who have worked in Waterbury up until now remain at SUSS MicroTec at least until the end of 2010 or the end of the first quarter of 2011. In addition, SUSS MicroTec plans to continue employing selected staff members from Waterbury temporarily in Sternenfels beyond the end of 2010 in order to retain as much expertise as possible. The SUSS MicroTec Group regards as a risk the possibility that this transfer of expertise may not occur to the extent needed. First, employees of SMT Inc. could leave the Company early and would therefore no longer be available to transfer knowledge. Second, selected employees of SMT Inc. in Waterbury may not be sufficiently willing to move temporarily to Sternenfels or California in order to provide active support in transferring expertise. In order to minimize this risk, a team from Germany currently consisting of 15 employees was assembled. This team is already working in Waterbury to support the transfer of expertise and acquire as much of the available knowledge and experience as possible by the end of the year. At the same time, selected employees in Waterbury were made attractive offers in order to incentivize them and increase their willingness to remain at SUSS MicroTec until the closure of the Waterbury site or (temporarily) move to Sternenfels and participate beyond 2010 in the reorganization and expansion of the Substrate Bonder division.

The SUSS MicroTec Group (via an ad hoc announcement on June 10, 2010) provided timely notification of the details and schedule of the relocation of the Substrate Bonder division and the North American sales and service organization. There is a potential risk that these plans will lead to uncertainty among customers, who could become reluctant to submit new orders. SUSS MicroTec is countering this risk by communicating openly and transparently with customers and providing information about all pending measures and their impact. Simultaneously, both the transfer team from Germany and the employees still working in Waterbury have been made aware of, and sensitized to, this risk. Furthermore, the planned investments and measures, which are quite substantial, indicate that SUSS MicroTec anticipates significant growth in the Substrate Bonder division in the months and years to come and is very keen to retain existing customers and acquire new ones. So far, neither cancellations nor delays in order entry have been reported in the Substrate Bonder division. Instead, some customers have even welcomed the relocation that is underway because they assume that the planned steps will lead to the strengthening of supplier relationships with SUSS MicroTec. Therefore, this risk is regarded as negligible.

Even after the relocation of the Substrate Bonder division from Waterbury to Sternenfels, SUSS MicroTec plans to maintain existing supplier relationships (primarily with US suppliers), given positive experience in the past. The risk exists that the supply chain could be disrupted in view of the geographical distance and transnational differences. Delays in order processing and production could result. SUSS MicroTec is countering this risk by keeping North American suppliers apprised of all steps in the move and actively involving them in the process of relocation. At the same time, SUSS MicroTec is offering suppliers support in processing export transactions and is helping them with transnational formalities.

Regarding other operating risks, there were no substantial changes to the risks and opportunities in the first half of 2010.

Financial Market Risks

At the SUSS MicroTec Group, financial market risks encompass credit risks, liquidity risks, and market price risks. The 2009 Annual Report provided an extensive description of these risks.

No substantial changes to these risks and opportunities occurred in the first half of the year.

Overall Risk

No risks that threaten the Company's existence were identified within the Group in the first half of the 2010 fiscal year. The continued existence of the Company was at no time endangered from a material assets and liquidity point of view.

Risk Management System

The risk management system described in the 2009 Annual Report continued to be used in the first half of 2010.

Report on Material Transactions with Related Parties

Regarding material transactions with related parties, we refer to the corresponding text in the selected explanatory notes of the SUSS MicroTec AG Interim Report as of June 30, 2010 (Note 11).

Forecast Report

The business environment in which SUSS MicroTec AG operates is influenced by regional and global economic conditions as well as industry developments. The following forecast report provides a short explanation of changes since the beginning of the year in terms of internal and external factors that both the Company and leading market and industry observers regard as essential for the development of the Company.

Overall Macroeconomic Conditions

The global economy recovered in the first half of 2010 more rapidly than had been anticipated even at the beginning of the year. Although the International Monetary Fund (IMF) had forecast global economic growth of 3.9% for 2010 at the beginning of the year, it raised its estimate at the beginning of July 2010 by 0.6 percentage points to 4.5%. The Kiel Institute for the World Economy (ifw) also significantly raised its forecast for global economic development in 2010 at mid-year from 3.7% to 4.4%. For the eurozone, both institutions are expecting an increase in gross domestic product compared with 2009 of between 1.0% (IMF) and 1.3% (ifw). Market researchers cited the continuing expansionary fiscal policies of most countries and the change in inventory management as reasons for the rapid, positive development. However, according to the ifw both factors will lose their stimulative effect or in the case of fiscal policy even have a restraining effect. Therefore, the trend will weaken slightly in 2011, according to economic experts.

The German Institute for Economic Research (DIW) has somewhat dampened expectations for the performance of the German economy in the next two years. As the reason for the adjustment, the DIW cited the continuing weakness in domestic demand (due to the high level of government debt) that has so far not kept pace with the anticipated strong level of foreign demand. Instead of the growth rate of 2.1% forecast at the beginning of the year, the Institute now expects an increase in economic output of 1.9% for 2010. For 2011, the DIW anticipates additional growth of 1.7% instead of the 1.8% forecast at the beginning of 2010.

Industry-specific Conditions

Semiconductor Industry

At the beginning of 2010, the two market research institutes Gartner and iSuppli anticipated global sales in the semiconductor market to grow by 19.9% and 21.5%, respectively, to between US$ 276 billion and US$ 280 billion (as of February/March 2010). At the beginning of June, Gartner significantly raised its annual forecast and now expects sales to grow by 27.1% to US$ 290 billion in the current year. As reasons for this optimism, Gartner cited the rising demand for PCs, cellular telephones, and consumer electronics as well as rising average prices for memory chips (DRAMs). For 2011, Gartner expects the global semiconductor market to continue to perform well and reach a sales level of US$ 307 billion.

Semiconductor Equipment Industry

At the beginning of 2010, market researchers predicted an increase in worldwide expenditures for semiconductor equipment, ranging from 45.3% (Gartner, December 2009) to 46.8% (iSuppli, January 2010). In mid-June 2010, Gartner raised its forecast significantly for the current year and now expects the global market for semiconductor equipment to grow by 113.2% to US$ 35.4 billion. In parallel, market researchers reduced their growth projections for 2011 to an increase of only 6.6%, following their assumptions in December 2009 that the market would grow by 30.2% to a total market volume of US$ 47.8 billion. However, when evaluating the figures, it should be noted that they reflect markets critical for major front-end-based manufacturers such as Applied Materials and ASML.

SUSS MicroTec, on the other hand, is not particularly active in the classic front-end of chip manufacturers. Instead, the Company primarily operates as an innovative, specialized equipment manufacturer in back-end semiconductor manufacturing and particularly in the niche markets of MEMS, advanced packaging, compound semiconductors, and 3D integration.

Expected Development on the Key Markets

As an innovative, specialized equipment manufacturer, SUSS MicroTec is primarily focused on the niche markets of advanced packaging, 3D integration, microelectromechanical systems (MEMS), and LED.

The projected development of these niche markets is detailed on pages 69-71 of the 2009 Annual Report. As of mid-2010, there have been no substantial changes to the assessments made there on the expected development of the niche markets. Therefore, we refer to the information in the Forecast Report section of the 2009 Annual Report.

At present, there is only a small number of market studies and forecasts for the three-dimensional system integration (3D integration) market, which is still in its infancy and is largely in development. In May 2010, the French market research institute Yole Développement published a study for the first time on the significance of wafer bonding processes in 3D integration. According to the study, both temporary and permanent wafer bonding represent manufacturing processes that will gain enormously in significance within the context of 3D integration in the future. The current study states that the market for temporary and permanent bonding will grow in the next two years from US$ 166.5 million in 2010 to US$ 533.3 million in 2013. This corresponds to an average annual growth rate of 79.0%.

SUSS MicroTec is focusing on the market for temporary and permanent bonding solutions with a broad portfolio of bonding equipment. According to its own estimates, SUSS MicroTec's current worldwide share of the bonder equipment market is approximately 30%.

Endogenous Indicators

Aside from the condition of the markets, the innovation potential of our product range is also a critical factor for our success. In the 2009 fiscal year, the Company concluded a total of four strategically important development cooperative agreements with well-known partners from industry and research in the area of 3D integration. Already in 2010, these innovations attracted the interest of research and development facilities as well as chip manufacturers. Therefore, we continue to assume that our customers will gradually integrate these new processes into their production in the coming years.

Statement on the Projected Development of the Group

The global economy recovered in the first half of 2010 more rapidly than leading market research institutes had anticipated at the beginning of the year.

During 2010, the Gartner market research institute significantly boosted its growth forecasts both for the global semiconductor market and the semiconductor equipment market. Although market researchers assumed sales growth of 45.3% in the semiconductor equipment market in December 2009, experts now expect the market volume to increase by 113.2% to US$ 35.4 billion in 2010. Even though these forecasts refer to markets that are crucial to large front-end-based manufacturers and are, therefore, less informative for the SUSS MicroTec Group, we have adjusted our forecast for the whole of 2010, taking into account the strong orders position in the first two quarters of the year. We now expect annual sales from continuing activities of almost €140 million as well as positive earnings before interest and taxes (EBIT) despite one-off restructuring expenses of approximately €7.5 million.

Furthermore, we assume that we will be able to generate positive free cash flow (before including the effects of M&A activities already carried out) in 2010 as well.

Forward-looking Statements

This Interim Report contains information and forecasts that refer to the future developments of the SUSS MicroTec Group and its companies. The forecasts are assessments that the Company has made based on all of the information available to it at the present time. Should the assumptions on which these forecasts are based not occur or the risks – as addressed in the risk report – arise, the actual results may deviate from those currently expected.

Garching, Germany, August 4, 2010

The Management Board

Frank Averdung
Chief Executive Officer

Michael Knopp
Chief Financial Officer

INTERIM FINANCIAL STATEMENTS

CONSOLIDATED STATEMENT OF INCOME (IFRS)

in € thousand	04/01/2010 – 06/30/2010	04/01/2009 – 06/30/2009
Sales	**37,739**	**24,636**
Cost of sales	-24,443	-14,913
Gross profit	**13,296**	**9,723**
Selling costs	-4,288	-4,328
Research and development costs	-1,843	-1,073
Administration costs	-5,036	-3,518
Other operating income	2,983	846
Other operating expenses	-1,610	-683
Analysis of net income from operations (EBIT):		
EBITDA (Earnings before Interest and Taxes, Depreciation and Amortization)	5,151	2,089
Depreciation and amortization of tangible assets, intangible assets and investments in subsidiaries	-1,649	-1,122
Net income from operations (EBIT)	**3,502**	**967**
Financial income/expense	-223	56
Proft or loss from continuing operations before taxes	**3,279**	**1,023**
Income taxes	-1,464	-300
Proft or loss from continuing operations	**1,815**	**723**
Net profit or loss from discontinued operations (after taxes)	**-206**	**-794**
Net profit or loss	**1,609**	**-71**
Thereof equity holders of SUSS MicroTec	1,596	-46
Thereof minority interests	13	-25
Earnings per share (undiluted)		
Basic earnings per share from continuing operations in €	0.10	0.04
Basic earnings per share from discontinued operations in €	-0.01	-0.05
Earnings per share (diluted)		
Basic earnings per share from continuing operations in €	0.10	0.04
Basic earnings per share from discontinued operations in €	-0.01	-0.05

CONSOLIDATED STATEMENT OF INCOME (IFRS)

in € thousand	01/01/2010 – 06/30/2010	01/01/2009 – 06/30/2009
Sales	**59,632**	**47,087**
Cost of sales	-39,522	-28,177
Gross profit	**20,110**	**18,910**
Selling costs	-7,654	-8,955
Research and development costs	-3,342	-2,341
Administration costs	-8,715	-7,008
Other operating income	5,467	2,018
Other operating expenses	-2,415	-2,459
Analysis of net income from operations (EBIT):		
EBITDA (Earnings before Interest and Taxes, Depreciation and Amortization)	6,768	2,555
Depreciation and amortization of tangible assets, intangible assets and investments in subsidiaries	-3,317	-2,390
Net income from operations (EBIT)	**3,451**	**165**
Financial income/expense	-495	7
Proft or loss from continuing operations before taxes	**2,956**	**172**
Income taxes	-1,851	-502
Proft or loss from continuing operations	**1,105**	**-330**
Net profit or loss from discontinued operations (after taxes)	**-570**	**-814**
Net profit or loss	**535**	**-1,144**
Thereof equity holders of SUSS MicroTec	512	-1,104
Thereof minority interests	23	-40
Earnings per share (undiluted)		
Basic earnings per share from continuing operations in €	0.06	-0.02
Basic earnings per share from discontinued operations in €	-0.03	-0.05
Earnings per share (diluted)		
Basic earnings per share from continuing operations in €	0.06	-0.02
Basic earnings per share from discontinued operations in €	-0.03	-0.05

STATEMENT OF COMPREHENSIVE INCOME (IFRS)

in € thousand	01/01/2010 – 06/30/2010	01/01/2009 – 06/30/2009
Net profit or loss	**535**	**-1,144**
Fair value fluctuations of available for sale securities	390	224
Foreign currency adjustment	3,548	366
Cash flow hedges	0	-289
Deferred taxes	-639	19
Total income and expenses recognized in equity	**3,298**	**320**
Total income and expenses reported in the reporting period	**3,833**	**-824**
Thereof equity holders of SUSS MicroTec	3,779	-777
Thereof minority interests	54	-47

CONSOLIDATED BALANCE SHEET (IFRS)

ASSETS in € thousand	06/30/2010	12/31/2009
Non-current assets	**45,331**	**39,954**
Intangible assets	14,340	13,837
Goodwill	13,599	13,599
Tangible assets	8,845	4,081
Current tax assets	121	121
Other assets	541	554
Deferred tax assets	7,885	7,762
Current assets	**116,807**	**96,480**
Inventories	56,711	40,790
Accounts receivable	16,630	14,842
Other financial assets	1,070	355
Securities	20,301	10,489
Current tax assets	87	265
Cash and cash equivalents	19,496	20,621
Other assets	2,512	1,595
Assets classified as held for disposal	0	7,523
Total assets	**162,138**	**136,434**

LIABILITIES & SHAREHOLDERS' EQUITY in € thousand	06/30/2010	12/31/2009
Equity	**96,646**	**86,060**
Total equity attributable to shareholders of SUSS MicroTec AG	96,391	85,859
Subscribed capital	18,721	17,019
Reserves	75,146	69,583
Accumulated other comprehensive income	2,524	-743
Minority interests	255	201
Non-current liabilities	**21,048**	**19,988**
Pension plans and similar commitments	3,145	3,003
Provisions	639	711
Financial debt	10,510	10,962
Other financial liabilities	74	67
Deferred tax liabilities	6,680	5,245
Current liabilities	**44,444**	**30,386**
Provisions	4,554	1,772
Tax liabilities	1,944	595
Financial debt	988	1,747
Other financial liabilities	4,527	4,536
Accounts payable	11,136	4,458
Other liabilities	21,295	14,906
Liabilities associated with assets classified as held for disposal	0	2,372
Total liabilities and shareholders' equity	**162,138**	**136,434**

CONSOLIDATED STATEMENT OF CASH FLOWS (IFRS)

in € thousand	01/01/2010 – 06/30/2010	01/01/2009 – 06/30/2009
Net profit or loss (after taxes)	535	-1,144
Amortization of intangible assets	2,080	1,792
Depreciation of tangible assets	1,251	743
Profit or loss on disposal of intangible and tangible assets	10	20
Change of reserves on inventories	-80	1,335
Change of reserves for bad debts	45	-410
Non-cash stock based compensation	93	103
Non-cash income from the reversal of provisions	-196	-242
Other non-cash effective income and expenses	-1,826	10
Bargain purchase arising from acquisition Hamatech	-2,678	0
Gain from deconsolidation of SMTTS	-781	0
Change in inventories	-7,642	315
Change in accounts receivable	1,812	11,528
Change in other assets	-877	-608
Change in pension provisions	257	-43
Change in accounts payable	4,425	104
Change in other liabilities and other provisions	8,527	-7,453
Change of deferred taxes	1,501	379
Cash flow from operating activities – continuing and discontinued operations	**6,456**	**6,429**
Cash flow from operating activities – continuing operations	**6,456**	**6,513**

in € thousand	01/01/2010 – 06/30/2010	01/01/2009 – 06/30/2009
Disbursements for tangible assets	-1,016	-181
Disbursements for intangible assets	-206	-2,269
Purchases of current available-for-sale securities	-8,092	-4,051
Proceeds from redemption of available-for-sale securities	1,014	0
Payments for purchase of Hamatech	-8,771	0
Proceeds from disposal of Test business	2,708	0
Cash flow from investing activities – continuing and discontinued operations	**-14,363**	**-6,501**
Cash flow from investing activities – continuing operations	**-14,363**	**-6,490**
Repayment of bank loans	0	-42
Change in current bank liabilities	-759	-2,341
Change in other financial debt	-452	-60
Proceeds from share capital contribution	6,808	0
Payments for expenses related to capital contribution	-205	0
Cash flow from financing activities – continuing and discontinued operations:	**5,392**	**-2,443**
Cash flow from financing activities – continuing operations:	**5,392**	**-2,443**
Adjustments to funds caused by exchange-rate fluctuations	1,212	223
Change in cash and cash equivalents	**-1,303**	**-2,292**
Funds at beginning of the year*	20,799	20,603
Funds at end of the period	**19,496**	**18,311**
Cash flow from operating activities includes:		
Interest paid during the period	52	70
Interest received during period	253	335
Tax paid during the period	218	512
Tax refunds during the period	64	132

* Cash and Cash equivalents as of January 1, 2010 also includes cash assets attributable to available-for-sale assets and discontinued activities (€178 million).

CONSOLIDATED STATEMENT OF SHAREHOLDERS' EQUITY (IFRS)

in € thousand	Subscribed capital	Additional paid-in capital
As of January 01, 2009	**17,019**	**92,842**
Issuance of subscription rights		103
Net profit loss or loss		
Total income and expenses recognized in equity		
As of June 30, 2009	**17,019**	**92,945**
As of January 01, 2010	**17,019**	**93,094**
Capital increase	1,702	4,959
Issuance of subscription rights		93
Net profit loss or loss		
Total income and expenses recognized in equity		
As of June 30, 2010	**18,721**	**98,146**

Earnings reserve	Retained Earnings	Accumulated other Comprehensive Income	Total equity attributable to shareholders of SUSS MicroTec AG	Minority interests	Equity
433	**-19,133**	**-791**	**90,370**	**247**	**90,617**
			103		103
	-1,104		-1,104	-40	-1,144
		327	327	-7	320
433	**-20,237**	**-464**	**89,696**	**200**	**89,896**
433	**-23,945**	**-743**	**85,858**	**201**	**86,059**
					6,661
			93		93
	512		512	23	535
		3,267	3,267	31	3,298
433	**-23,433**	**2,524**	**96,391**	**255**	**96,646**

SEGMENT REPORTING (IFRS)

Segment information by business segment

	Lithography		Substrate Bonder		Photomask Equipment	
in € thousand	6M/2010	6M/2009	6M/2010	6M/2009	6M/2010	6M/2009
External Sales	38,498	36,017	12,060	8,746	6,053	0
Internal Sales	0	0	0	0	0	0
Total Sales	**38,498**	**36,017**	**12,060**	**8,746**	**6,053**	**0**
Result per segment (EBIT)	7,012	4,504	-4,084	-1,349	-172	0
Income before taxes	7,005	4,437	-4,087	-1,352	-172	0
Significant non-cash items	-444	-1,243	-1,005	-213	58	0
Segment assets	55,691	52,955	34,460	27,140	8,622	0
– thereof Goodwill	13,599	13,599	0	0	0	0
Unallocated assets						
Total assets						
Segment liabilities	-20,740	-15,281	-10,463	-6,627	-3,753	0
Unallocated liabilities						
Total liabilities						
Depreciation and amortisation	876	1,014	1,385	729	326	0
– thereof scheduled	801	1,014	1,252	729	326	0
– thereof impairment loss	75	0	133	0	0	0
Capital expenditure	281	562	373	632	1,973	0
Employees as of June 30	319	324	125	113	84	0

Segment information by region

	Sales		Capital expenditure		Assets	
in € thousand	6M/2010	6M/2009	6M/2010	6M/2009	6M/2010	6M/2009
Europe	13,767	22,570	6,700	1,791	72,028	67,790
North-America	9,730	9,831	559	644	32,379	32,282
Japan	5,454	7,141	21	11	2,249	3,704
Rest of Asia	31,991	14,694	74	4	1,578	1,083
Rest of world	114	28	53	0	0	0
Consolidation effects	0	0	0	0	1,890	-1,880
Total	**61,056**	**54,264**	**7,407**	**2,450**	**110,124**	**102,979**

Other		Continuing operations		Discontinued Operations (Test business)		Consolidation effects		Total	
6M/2010	6M/2009	6M/2010	6M/2009	6M/2010	6M/2009	6M/2010	6M/2009	6M/2010	6M/2009
3,021	**2,324**	**59,632**	**47,087**	**1,424**	**7,177**	-	-	**61,056**	**54,264**
2,829	2,501	2,829	2,501	0	0	-2,829	-2,501	0	0
5,850	**4,825**	**62,461**	**49,588**	**1,424**	**7,177**	**-2,829**	**-2,501**	**61,056**	**54,264**
695	-2,990	3,451	165	-571	-819	-	-	2,880	-654
210	-2,914	2,956	171	-572	-821	-	-	2,384	-650
-81	131	-1,472	-1,325	37	-248	-	-	-1,435	-1,573
11,351	10,965	110,124	91,060	0	11,919	-	-	110,124	102,979
0	0	13,599	13,599	0	4,168	-	-	13,599	17,767
								52,014	40,168
								162,138	**143,147**
-2,208	-3,977	-37,164	-25,885	0	-3,553	-	-	-37,164	-29,438
								-28,328	-23,813
								-65,492	**-53,251**
730	647	3,317	2,390	14	145	-	-	3,331	2,535
730	647	3,109	2,390	14	145	-	-	3,123	2,535
0	0	208	0	0	0	-	-	208	0
4,780	1,239	7,407	2,433	0	17	-	-	7,407	2,450
53	62	581	499	0	124	-	-	581	623

SELECTED EXPLANATORY NOTES

to the Consolidated Interim Report of SUSS MicroTec AG as of June 30, 2010

1. General Accounting Policies

The consolidated financial statements of SUSS MicroTec AG as of December 31, 2009 have been prepared in accordance with the International Financial Reporting Standards (IFRSs) applied by the International Accounting Standards Board (IASB) as of the closing date. In the consolidated interim financial statements as of June 30, 2010, which were prepared on the basis of International Accounting Standards (IAS) 34 "Interim Financial Reporting," the same accounting methods were applied as in the consolidated financial statements for the 2009 fiscal year.

All of the interpretations of the International Financial Reporting Interpretations Committee (IFRIC) in effect as of June 30, 2010 have been applied.

For additional information about specific accounting and measurement methods, please see the consolidated financial statements of SUSS MicroTec AG as of December 31, 2009.

The Group auditor, KPMG AG Wirtschaftsprüfungsgesellschaft, has neither audited nor reviewed the interim financial statements.

2. Changes in the Scope of Consolidation

The consolidated financial statements include the financial statements of SUSS MicroTec AG and of all material companies over which, independent of the level of its participatory investment, the proprietary company can exercise control (i.e. the control principle).

Compared with the consolidated financial statements as of December 31, 2009, the following changes were made to the scope of consolidation:

+ SUSS MicroTec AG sold the Test Systems division in accordance with the purchase agreement of January 27, 2010. The main component of the transaction was the complete sale of 100% of the shares in SUSS MicroTec Test Systems GmbH, located in Sacka near Dresden, Germany. SUSS MicroTec Test Systems GmbH was deconsolidated as of January 27, 2010.

+ With effect from February 15, 2010, SUSS MicroTec AG acquired 100% of the shares in HamaTech APE GmbH & Co. KG, based in Sternenfels, Germany, from Singulus Technologies AG. HamaTech APE GmbH & Co. KG was included in the consolidated financial statements for the first time in accordance with IAS 27 (rev. 2008) and IFRS 3 (rev. 2008) as of March 31, 2010.

There were no additional changes in the scope of consolidation.

3. Mandatory Disclosures

3.1 Sale of the Test Systems Division

On January 28, 2010, SUSS MicroTec AG announced the sale of the Test Systems division to Cascade Microtech Inc., which is based in Beaverton, Oregon (USA). The Test Systems division is located in Sacka, near Dresden. The site handles development, production, and distribution in Europe. In Asia and North America, sales are conducted via SUSS MicroTec subsidiaries or external representatives.

The main component of the transaction was the sale of all shares in SUSS MicroTec Test Systems GmbH. In addition, individual assets of foreign subsidiaries, also assigned to the Test Systems division, were sold.

The purchase price for the Test Systems division consisted of a fixed amount and an amount placed in escrow. The fixed component amounts to €4.5 million, of which €2.0 million was paid in cash and €2.5 million was paid in the common shares of the purchaser. An additional amount of €2.5 million has been placed in escrow and will be released to the seller upon meeting certain post-sale conditions. This could lead to a corresponding purchase price adjustment. As of June 30, 2010, €0.2 million had been released from the escrow account to SUSS MicroTec AG. In addition, SUSS MicroTec AG received €0.8 million in purchase price adjustments. The total amount of €1.0 million had already been taken into account in the previous year in the measurement of available-for-sale assets and liabilities.

On January 27, 2010, SUSS MicroTec Test Systems GmbH was deconsolidated. The gain from the deconsolidation amounted to €0.8 million. Overall, the EBIT of the Test Systems division (discontinued activities) in the first half of 2010 was €-0.6 million.

3.2 Purchase of HamaTech APE GmbH & Co. KG

Effective February 15, 2010, SUSS MicroTec AG acquired 100% of the shares in HamaTech APE GmbH & Co. KG, based in Sternenfels, Germany, from Singulus Technologies AG. In addition, SUSS MicroTec AG acquired the land and company buildings at the Sternenfels site as well as a company loan of approximately €10.1 million.

The purchase price for the land and company buildings totaled €4.5 million. The purchase price for the shares in HamaTech APE GmbH & Co. KG and the company loan is comprised of a fixed component of approximately €3.5 million and an earn-out component of €1 million. In addition, SUSS MicroTec AG eliminated additional inter-company receivables of Singulus Technologies AG of approximately €1.0 million, which had resulted from the ongoing operations of HamaTech APE GmbH & Co. KG since January 1, 2010. Already in the first quarter of 2010, SUSS MicroTec AG had paid the entire (fixed) purchase price of approximately €9.0 million.

The acquisition of the shares and assets or liabilities is recorded in the consolidated financial statements of SUSS MicroTec AG in accordance with the International Financial Reporting Standards as a business combination, as stipulated in IAS 27 (rev. 2008) and IFRS 3 (rev. 2008). In this context, the acquired assets, liabilities, and contingent liabilities (with a few exceptions) are to be recognized at fair value at the time of acquisition (IFRS 3.18). In accordance with the guidelines of IFRS 3 in connection with IAS 38, not only assets appearing in the statement of financial position are to be taken into account, but also not yet recognized intangible assets.

Against this background, a purchase price allocation was conducted for the acquired assets and liabilities. The acquired assets and liabilities were recognized at the time of initial consolidation as follows:

in € million	Book value according to IFRS	At time of acquisition
Intangible assets	3.1	1.3
Tangible assets	0.3	0.4
Current assets	7.6	7.6
Total assets	**11.0**	**9.3**
Noncurrent liabilities	0.0	0.0
Current liabilities	2.6	2.6
Total liabilities	**2.6**	**2.6**
Net assets	8.4	6.7
Acquisition costs		4.5
Provision for earn-out		0.8
Bargain purchase		1.4

Capitalized development costs of €2.7 million, which previously had been recognized under intangible assets, were measured at the time of acquisition at €0. Instead, previously unrecognized intangible assets of €0.9 million, which primarily related to the acquired technology, were capitalized. The measurement of the technology is based on planning for the years 2010 to 2013 and the resulting cash flows. In addition, hidden reserves within tangible assets of €0.1 million were disclosed.

As part of the purchase of HamaTech APE GmbH & Co. KG, the seller, Singulus Technologies AG, issued a shareholders' equity guarantee to the effect that the shareholders' equity of HamaTech APE GmbH & Co. KG calculated in accordance with the German Commercial Code (HGB) should not fall below a certain amount at the time of closing. From SUSS MicroTec's perspective, the shareholders' equity guarantee was violated. As part of a settlement agreement, the buyer and seller agreed on a settlement in the form of a retroactive purchase price adjustment. First, Singulus Technologies AG will refund €0.7 million of the purchase price already received to SUSS MicroTec AG. And second, the earn-out component will be reduced from the previous amount of €1 million to €0.3 million. The settlement agreement has resulted in a positive impact on earnings of €1.2 million for the second quarter of 2010.

As a result of the settlement agreement with Singulus Technologies AG, the provision for the earn-out component has been reduced to €0.3 million. Gain of bargain purchase has increased to €2.7 million. Gain of bargain purchase is recognized with effect on net income under other operating income in accordance with IFRS 3.34.

HamaTech APE GmbH & Co. KG's income and expenses in the months from March to June 2010 are recorded in the consolidated statement of income. In this period, HamaTech APE contributed sales of €5.7 million and earnings of €0.1 million to consolidated earnings after taxes. If SUSS MicroTec AG had already acquired HamaTech at the beginning of the reporting period, consolidated sales would have totaled €59.9 million and consolidated earnings after taxes €0.0 million.

3.3 Increase in Capital Stock

In May 2010, SUSS MicroTec AG approved an increase in capital stock without subscription rights from approved capital, which was completed on May 11, 2010. 1,701,912 shares with profit-sharing rights were placed, beginning on January 1, 2010 at a price of €4.00 per share. The gross inflow of funds amounted to €6.8 million.

The Company's equity capital was increased from €17,019,126.00 (divided into 17,019,126 common bearer shares with a calculated par value of €1.00 per share) by an amount of €1,701,912.00 to €18,721,038.00. Additional paid-in capital increased (gross) by €5.1 million.

The transaction costs for carrying out the increase in capital stock totaled approximately €0.2 million. They were deducted from additional paid-in capital.

3.4 Strategic Restructuring

On June 10, 2010, SUSS MicroTec AG announced its decision to relocate its Substrate Bonder division, which is currently based in Waterbury, Vermont (USA), to Germany this year. In the course of the planned restructuring, the research and development, production and product management functions of the Bonder product lines will be moved to the production site in Sternenfels, Germany. At the same time, the North American service and sales activities as well as the applications center will be moved from Waterbury, VT, to Silicon Valley in California.

The expected restructuring costs will reach approximately €7.5 million and will impact primarily on 2010. In the first half of 2010, approximately €0.8 million in restructuring expenses were recorded. As of June 30, 2010, provisions for restructuring came to €0.7 million.

3.5 New Credit Agreements

On March 31, 2010, the previous bank consortium led by Fortis Bank was replaced by a new consortium led by Bayern LB. In March 2010, SUSS MicroTec AG signed credit agreements with the new bank consortium for a credit line of €6 million. The credit line initially runs until February 28, 2011 and was issued without covenants. Its primary purpose is to serve as backing for down payment guarantees.

In May 2010, HamaTech APE GmbH & Co. KG concluded a general credit agreement with BW Bank Mannheim for a credt line of €1 million. The credit line runs for an indefinite term and was issued without covenants. SUSS MicroTec AG issued a binding letter of comfort for HamaTech APE GmbH & Co. KG in order to secure the credit line.

3.6 Other Mandatory Disclosures

The securities recognized in the statement of financial position include corporate and government bonds as well as commercial paper. The corporate and government bonds have been measured at market prices. Any fluctuations in the market price are recognized in accumulated other comprehensive income and therefore do not affect profit and loss.

Also disclosed under this item in the statement of financial position are the 747,530 Cascade shares – with a fair value of €2.7 million as of June 30, 2010 – obtained through the sale of the Test Systems division. Fluctuations in the market price are recognized in accumulated other comprehensive income and therefore do not affect profit and loss.

Other issues influencing assets, liabilities, shareholders' equity, the result for the period, or cash flows and unusual in terms of their nature, magnitude, or frequency, did not arise during the interim reporting period.

4. Change in Presentation

The presentation of the consolidated financial statements as of June 30, 2010 is analogous to the presentation as of December 31, 2009. There were no changes in presentation.

5. Changes in Estimates

To the extent that estimates were made in the interim reports, the methodology underlying the estimates remained fundamentally the same during the fiscal year and in comparison to the previous fiscal year.

In a departure from the approach used at the end of the fiscal year, income tax expense in each interim reporting period is recorded on the basis of the best estimate of the weighted average annual income tax rate which is expected for the entire fiscal year.

SUSS MicroTec AG currently assumes that the annual income tax rate will deviate from the expected tax rate of approximately 28%. The primary reason for this is that the losses accrued by foreign subsidiaries cannot be capitalized.

Otherwise there are no changes requiring disclosure which would have a material impact on the current interim reporting period.

6. Bonds and Equity Securities

An increase in capital stock from approved capital was undertaken during the reporting period. No additional issuances, repurchases, or repayments occurred involving either bonds or equity securities.

7. Dividends Paid

During the reporting report, no dividend was distributed nor was such a distribution proposed.

8. Significant Events After the End of the Interim Reporting Period

On May 25/28, 2010, SUSS MicroTec AG concluded a loan agreement with a local bank in order to finance the newly acquired business property in Sternenfels. The loan, which totals €4.5 million, has a term until June 30, 2020. It was made available and drawn down on July 6, 2010.

No additional material events occurred after the end of the interim reporting period.

9. Contingent Liabilities and Receivables

There are no contingent receivables. There were no substantial changes in contingent liabilities since the reporting date of December 31, 2009.

10. Earnings per Share

Basic earnings per share are calculated by dividing the net profit or loss for the period (net of minority interests) by the average number of shares.

For the first half of 2010, the average weighted number of shares – taking into account the increase in capital stock during the year – was 17,414,045 shares.

In order to calculate diluted earnings per share, the profit or loss for the period attributable to shareholders (net of minority interests) and the weighted average of outstanding shares are adjusted for the impact of all potential dilutive shares.

The existing stock option plans were not taken into account in calculating diluted earnings per share because either the market price of the SUSS MicroTec share was less than the exercise price of the options (the options were not "in the money") or the options could be exercised only given certain conditions, which were not met in full as of the reporting date.

11. Related Parties

In the previous year the Group was affected by the disclosure requirements of IAS 24 "Related Party Disclosures" with respect to business relationships with the since resigned Chairman of the Supervisory Board of SUSS MicroTec AG. The former Chairman of the Supervisory Board, Dr. Richter, was simultaneously a Management Board member of Thin Materials AG in Eichenau, Germany. In the first quarter of 2009, SUSS MicroTec AG concluded a cooperation agreement with this company. The agreement governs cooperation between the two companies in the area of thin wafer processing. As part of the agreement, SUSS MicroTec AG acquired intellectual property (IP) and expertise in the area of thin wafer handling for €0.9 million. The capitalized IP will be amortized over five years. At last year's SUSS MicroTec AG's Shareholders' Meeting on June 24, 2009, Dr. Richter resigned from his position as Chairman of the Supervisory Board of the Company.

RESPONSIBILITY STATEMENT BY THE BOARD OF MANAGEMENT

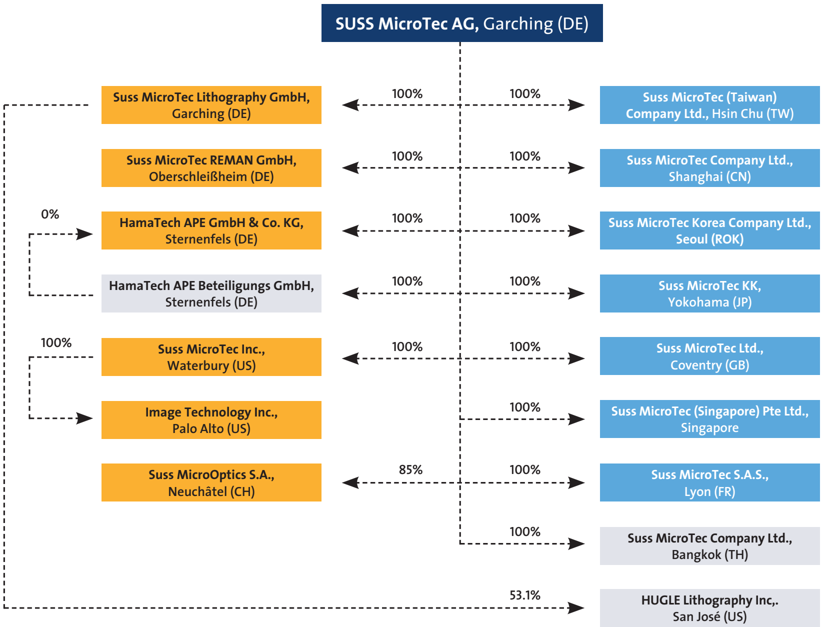
"To the best of our knowledge, and in accordance with the applicable reporting principles, the consolidated interim financial statements give a true and fair view of the assets, liabilities, financial position, and profit or loss of the Group, and the Group Interim Management Report includes a fair review of the development and performance of the business and the position of the Group, together with a description of the principal opportunities and risks associated with the expected development of the Group over the remainder of the fiscal year."

Garching, August 4, 2010

Frank Averdung
CEO

Michael Knopp
CFO

LEGAL STRUCTURE OF THE GROUP



Holding Company

Sales

Production

Other / Non-operating

FINANCIAL CALENDAR 2010

Interim Report 2010	August 5
6th UBS Best of Germany Conference, New York, USA	September 15–16
8th Scherrer Conference, Zurich, Switzerland	September 30
Nine-month Report 2010	November 04
Analysts' Conference at the German Equity Forum Fall 2010	November 22–24
UBJ Investor Conference, Hamburg	Dezember 02

CREDITS AND CONTACT

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